

ELECTRONICALLY FILED ON 25 SEPTEMBER 2006

***IN THE UNITED STATES PATENT AND TRADEMARK OFFICE***

In re application of: Marcos Karnezos	Attorney Docket No.: CPAC 1017-3 D1
Application No.: 10/632,568	Examiner: Douglas M. Menz
Filed: 02 August 2003	Group: 2891
Title: Semiconductor Multi-Package Module Having Wire Bond Interconnect Between Stacked Packages And Having Enhanced Heat Dissipation	Confirmation No.: 2603
	<b>Customer No. 22470</b>

**INFORMATION DISCLOSURE STATEMENT**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

It is requested that the information identified in this statement be considered by the Examiner and made of record in the above-identified application. This statement is not intended to represent that a search has been made or that the information cited in the statement is, or is considered to be, material to patentability as defined in 37 C.F.R. 1.56.

Enclosed with this statement is a Form PTO/SB/08A. The Examiner is requested to initial the form and return it to the undersigned in accordance with M.P.E.P. 609.

Also enclosed with this statement is a copy of each cited document as required by 37 C.F.R. 1.98. However, since this application was filed after June 30, 2003, copies of U. S. Patents and U. S. Patent Application Publications are not enclosed. (See O. G. Notice of August 5, 2003.)

This statement should be considered under 37 C.F.R. 1.97(c) because it is being filed before the mailing date of a FINAL office action, a Notice of Allowance, or an action that otherwise closes prosecution in the subject application, whichever occurs first, AND:

This statement is accompanied by the \$180 fee set forth in 37 C.F.R. 1.17(p).

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**Fee Authorization.** The Commissioner is hereby authorized to charge any additional fees or credit any overpayment associated with this communication to Deposit Account No. 50-0869 (CPAC 1017-3 D1). A duplicate copy of this authorization is enclosed.

Respectfully submitted,  
Haynes Beffel & Wolfeld LLP

Date: 25 September 2006

By:  Reg. No. 33,407

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Sheet 1 of 1

Date  
Considered